

# ULTRASONIC

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Fully integrated ultrasonic system for thermo- and ultrasonic applications. The combination of the ultrasonic transducer and **Tresky's True Vertical Technology™**, which guarantees parallelism between chip and substrate as well as controlled bond force at every height, ensures a high quality and reliable bonding. Rotatable ultrasonic unit for easy handling and accurate alignment.

**40W** or **100W**, 90 kHz digital generator with continuous power adjustment. The ultrasonic power and time are programmable at the **T-5000** Series. The 40W unit can be used for bond forces up to 3500g and the 100W version up to 35Kg.

All TRESKY models can be upgraded with the Ultrasonic and further options.

#### OPTIONS:

- Various heating plates for substrate
- Inert gas chamber available for critical processes

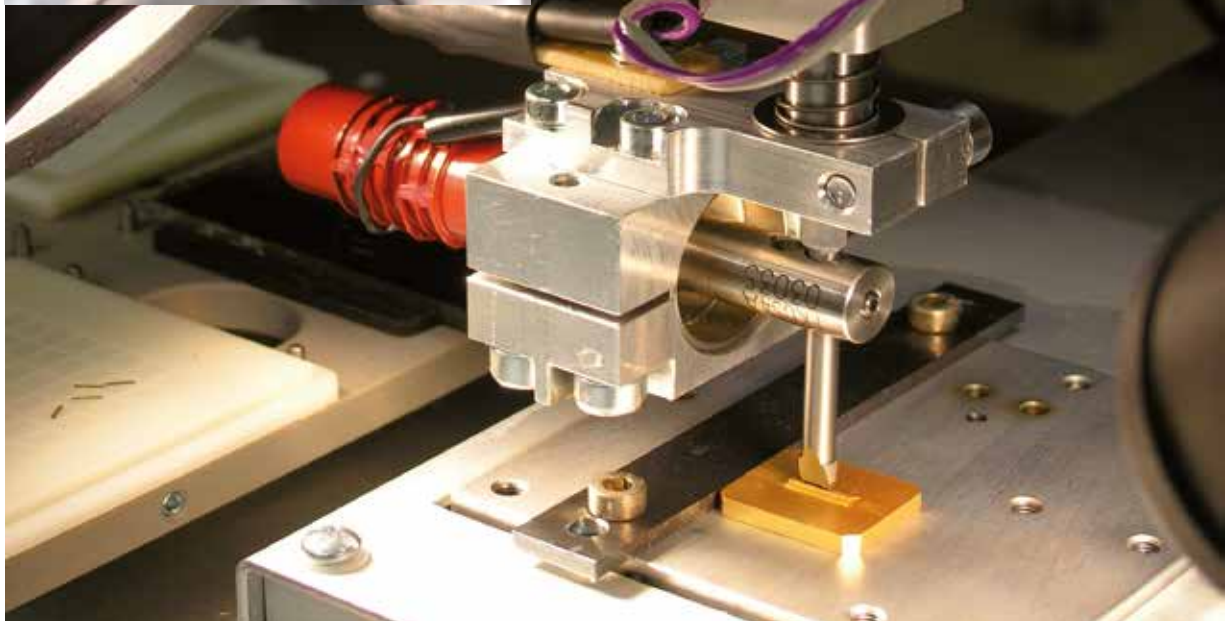
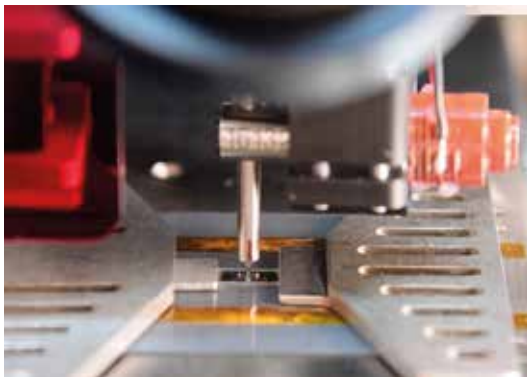
Thermosonic

High power

MICRO ASSEMBLY

OPTION

Tresky's True Vertical Technology™



# TRESKY

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